

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
MARK VAN DAL	06/11/2014
MARTIN CHRISTOPHER HOLLAND	06/11/2014
MATTHIAS PASSLACK	06/11/2014
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
<b>Street Address:</b>	NO. 8, LI-HSIN RD. 6
<b>Internal Address:</b>	SCIENCE-BASED INDUSTRIAL PARK
<b>City:</b>	HSIN-CHU
<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	300-77
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	14304695
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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<b>Correspondent Name:</b>	HAYNES AND BOONE, LLP
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<b>Address Line 4:</b>	DALLAS, TEXAS 75209
<b>ATTORNEY DOCKET NUMBER:</b>	24061.2859
<b>NAME OF SUBMITTER:</b>	BRIAN D. GRAHAM
<b>SIGNATURE:</b>	/Brian D. Graham/
<b>DATE SIGNED:</b>	06/18/2014
<b>Total Attachments: 2</b>	
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source=240612859Assn#page2.tif	

**ASSIGNMENT**

WHEREAS, we,

- (1) Mark van Dal of Nachtegalenstraat 52, 3210 Linden, Belgium
- (2) Martin Christopher Holland of Tervuursesteenweg 547, Leefdaal  
3061 Bertem, Belgium
- (3) Matthias Passlack of Kleinwaverstraat 14, 3040 Huldenberg, Belgium

have invented certain improvements in

**THIN-SHEET FINFET DEVICE**

for which we have executed an application for Letters Patent of the United States of America,

\_\_\_\_\_ of even date filed herewith; and

X filed on June 13, 2014 and assigned application number 14/304,695; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the

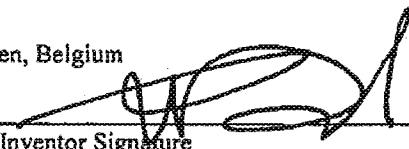
said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

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Inventor Name: Mark van Dal

Residence Address: Nachtegalenstraat 52, 3210 Linden, Belgium

Dated: 11-6-2014

  
Inventor Signature

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Inventor Name: Martin Christopher Holland

Residence Address: Tervuursesteenweg 547, Leefdaal, 3061 Bertem, Belgium

Dated: 11-6-2014

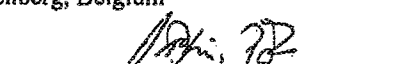
  
Inventor Signature

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Inventor Name: Matthias Passlack

Residence Address: Kleinwaverstraat 14, 3040 Huldenberg, Belgium

Dated: June 11 2014

  
Inventor Signature